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Adhesives Technology for Electronic Applications—James J. Licari 2011-06-24 Adhesives are widely used in the manufacture and assembly of electronic circuits and products. Generally, electronics design engineers and manufacturing engineers are not well versed in adhesives, while adhesive chemists have a limited knowledge of electronics. This book bridges these knowledge gaps and is useful to both groups. The book includes chapters covering types of adhesive, the chemistry on which they are based, and their properties, applications, processes, specifications, and reliability. Coverage of toxicity, environmental impacts and the regulatory framework make this book particularly important for engineers and managers alike. The third edition has been updated throughout and includes new sections on nanomaterials, environmental impacts and now environmentally friendly ‘green’ adhesives. Information about regulations and compliance has been brought fully up-to-date. As well as providing full coverage of standard adhesive types, Licari explores the most recent developments in fields such as: • Tamper-proof adhesives for electronic security devices. • Bio-compatible adhesives for implantable medical devices. • Electrically conductive adhesives to replace toxic tin-lead solders in printed circuit assembly – as required by regulatory regimes, e.g. the EU’s Restriction of Hazardous Substances Directive or RoHS (compliance is required for all products placed on the European market). • Nano-fillers in adhesives, used to increase the thermal conductivity of current adhesives for cooling electronic devices. A complete guide for the electronics industry to adhesive types, their properties and applications — this book is an essential reference for a wide range of specialists including electrical engineers, adhesion chemists and other engineering professionals. Provides specifications of adhesives for particular uses and outlines the processes for application and curing - coverage that is of particular benefit to design engineers, who are charged with creating the interface between the adhesive material and the microelectronic device Discusses the respective advantages and limitations of different adhesives for a varying applications, thereby addressing reliability issues before they occur and offering useful information to both design engineers and Quality Assurance personnel.